BYC12MX-650P

Hyperfast power diode

Rev.02 - 27 January 2026 | Product data sheet

1. General description

Hyperfast power diode in a TO220F-2L plastic package.

2. Features and benefits

- Fast switching
- Isolated plastic package
- Low leakage current
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses in associated MOSFET or IGBT

3. Applications

- Active PFC in air conditioner
- High frequency switched-mode power supplies
- Continuous Current Mode (CCM) Power Factor Correction (PFC)

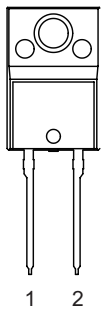
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage			650			V
$I_{F(AV)}$	average forward current	δ = 0.5 ; square-wave pulse; Fig. 1; Fig. 2		12			A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; square-wave pulse		24			A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 3		135			A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		148			A
Symbol	**Parameter**	**Conditions**	**Notes**	**Min**	**Typ**	**Max**	**Unit**
Static characteristics							
V_F	forward voltage	I_F = 12 A; T_j = 25 °C; Fig. 5		-	2.60	3.30	V
		I_F = 12 A; T_j = 150 °C; Fig. 5		-	1.60	2.30	V
Dynamic characteristics							
t_{rr}	reverse recovery time	I_F = 1 A; V_R = 30 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 6		-	14	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	n.c.	mounting base; isolated		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYC12MX-650P	TO220F-2L	BYC12MX-650PQ	Tube	50	TO220Fd-2L	02-Aug-2022

7. Marking

Table 4. Marking codes

Type number	Marking codes
BYC12MX-650P	BYC12MX 650P

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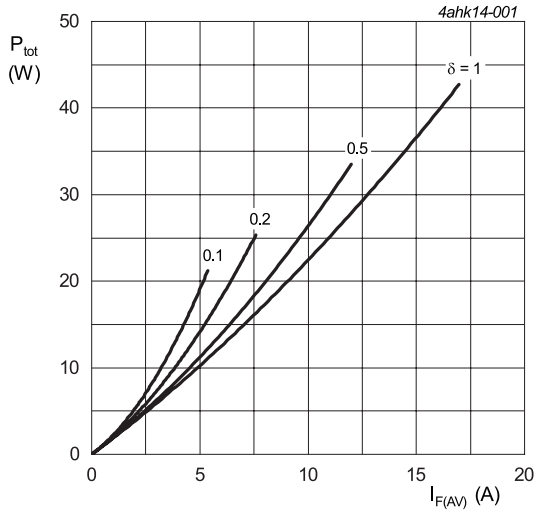
8. Limiting values

Table 5. Limiting values

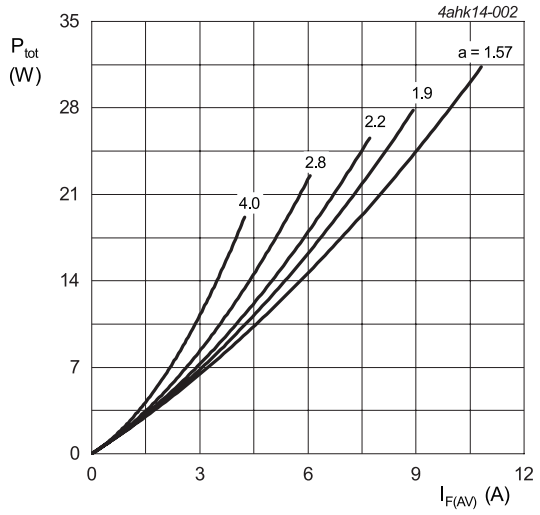
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			650	V
V_{RWM}	crest working reverse voltage			650	V
V_R	reverse voltage	DC		650	V
$I_{F(AV)}$	average forward current	δ = 0.5 ; square-wave pulse; Fig. 1; Fig. 2		12	A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; square-wave pulse		24	A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 3		135	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		148	A
T_{stg}	storage temperature			-65 to 175	°C
T_j	junction temperature			-65 to 175	°C



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$
V_o = 1.852 V; R_s = 0.0392 Ω

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor = $I_{F(RMS)} / I_{F(AV)}$
V_o = 1.852 V; R_s = 0.0392 Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

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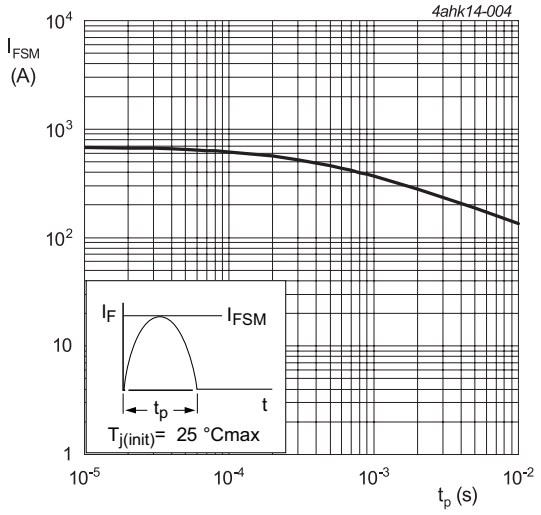

Fig. 3. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

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9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; Fig 4		-	-	4.8	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

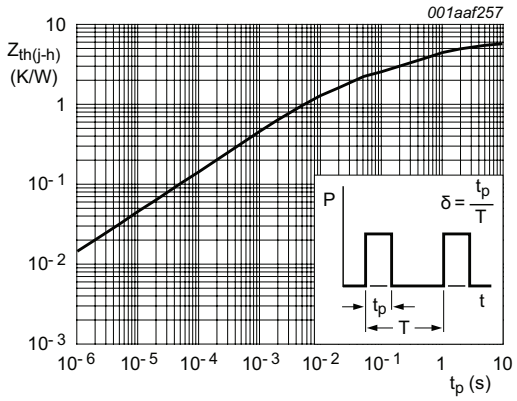

Fig. 4. Transient thermal impedance from junction to heatsink as a function of pulse duration

10. Isolation characteristics

Table 7. Isolation characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free		-	-	2500	V
C_{isol}	isolation capacitance	f = 1 MHz; from cathode to external heatsink		-	10	-	pF

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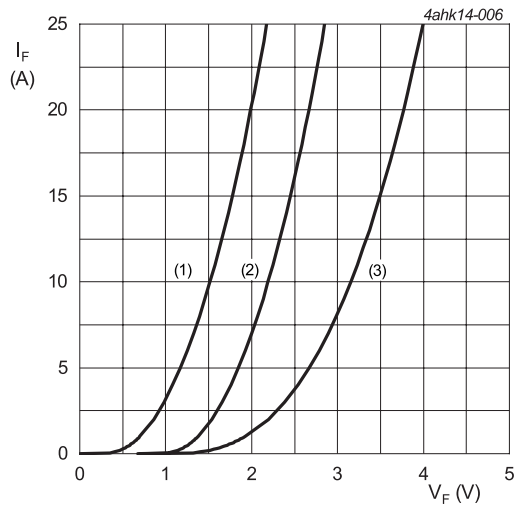
11. Characteristics

Table 8. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	I_F = 12 A; T_j = 25 °C; Fig. 5		-	2.60	3.30	V
		I_F = 12 A; T_j = 150 °C; Fig. 5		-	1.60	2.30	V
I_R	reverse current	V_R = 650 V; T_j = 25 °C		-	0.5	30	µA
		V_R = 650 V; T_j = 150 °C		-	-	0.8	mA
Dynamic characteristics							
Q_r	reverse charge	I_F = 12 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 6		-	37	-	nC
		I_F = 12 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 6		-	126	-	nC
t_{rr}	reverse recovery time	I_F = 0.5 A; I_{rr} = 0.25 A; I_R = 1 A; T_j = 25 °C; Fig. 6		-	20	-	ns
		I_F = 1 A; V_R = 30 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 6		-	14	-	ns
		I_F = 12 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 6		-	29	-	ns
		I_F = 12 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 6		-	50	-	ns
I_{RM}	peak reverse recovery current	I_F = 12 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 6		-	2.5	-	A
		I_F = 12 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 6		-	5.1	-	A
E_{as}	non-repetitive avalanche energy	$T_{j(init)}$ = 25 °C		10.8	-	-	mJ



V_o = 1.852 V; R_s = 0.0392 Ω
(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 5. Forward current as a function of forward voltage

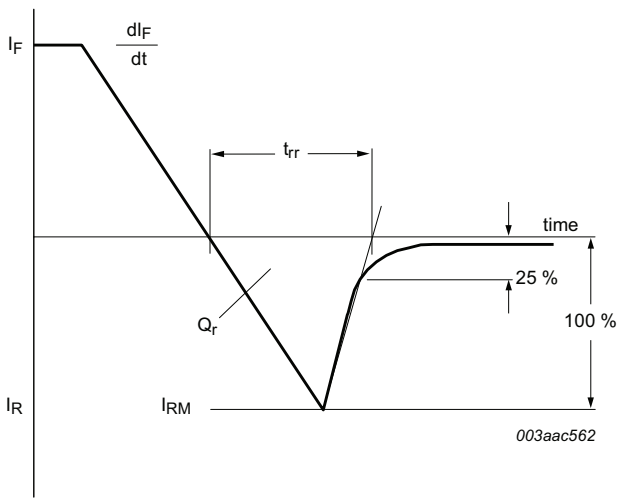


Fig. 6. Reverse recovery definitions; ramp recovery

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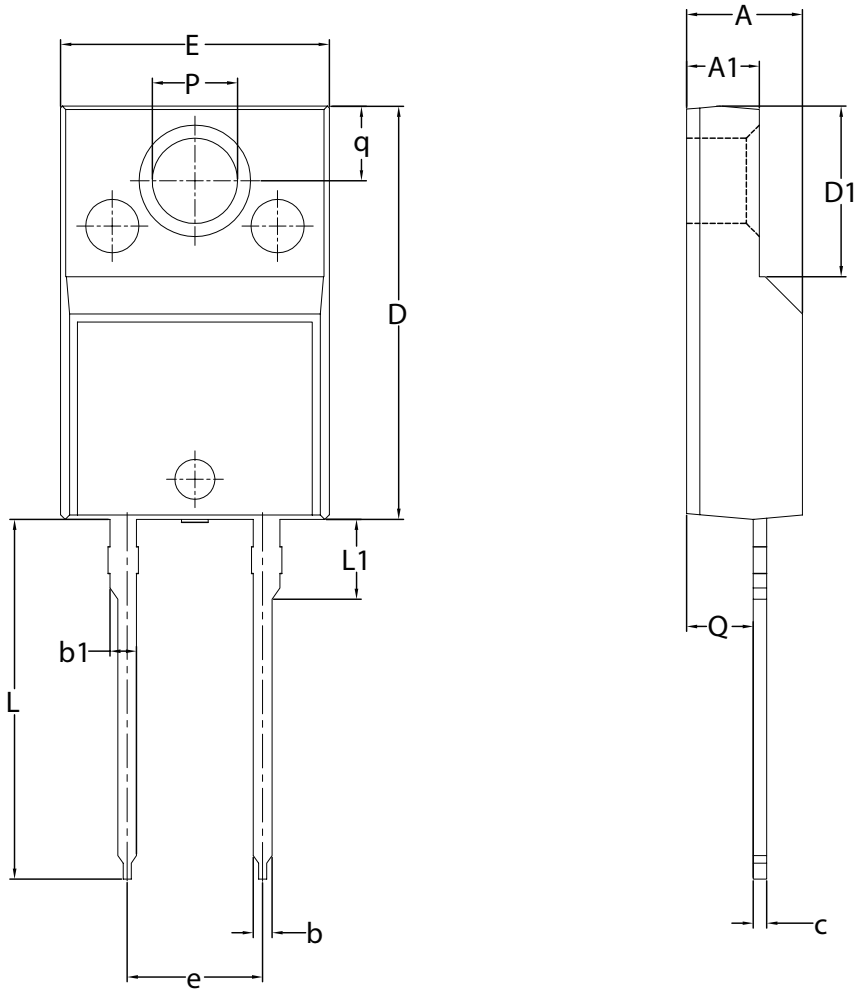
12. Package outline

Plastic single-ended package; isolated heatsink mounted;1 mounting hole; 2 leads TO-220 'full pack' TO220F-2L



Unit		A	A1	b	b1	c	D	D1	E	e	L	L1	P	Q	q
MM	min	4.00	2.50	0.70	0.90	0.40	15.20	6.30	9.80	5.08 (BSC)	13.50	2.80	3.00	2.30	2.60
	max	4.60	3.10	0.90	1.10	0.70	15.80	6.50	10.30		14.40	3.30	3.40	2.80	3.00

Note:
1. All dimensions don't include mold flash and metal protrusion.

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